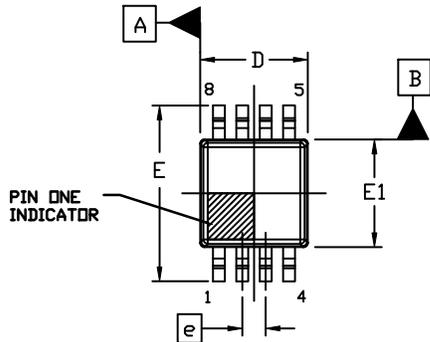
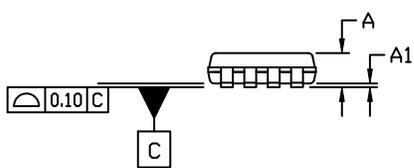


MSOP8 EP 3x3  
CASE 846AT  
ISSUE O

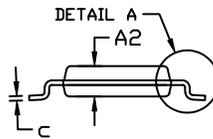
DATE 01 OCT 2020



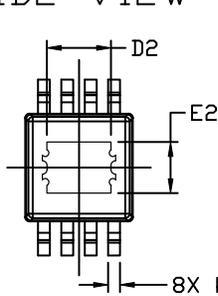
TOP VIEW



SIDE VIEW



END VIEW



BOTTOM VIEW

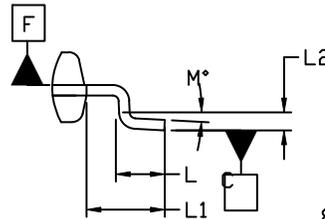
$\phi 0.08$  M C B A

NOTE 3

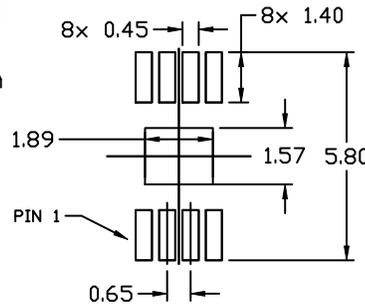
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.10 mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS b AND c APPLY TO THE PLATED LEADS.
5. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. DIMENSION E DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 mm PER SIDE. DIMENSIONS D AND E ARE DETERMINED AT DATUM F.
6. DATUMS A AND B ARE TO BE DETERMINED AT DATUM F.
7. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
8. PIN 1 INDICATOR IS LOCATED HERE. MAY APPEAR AS A LASER MARKED, OR A MOLDED (CIRCLE OR HALF MOON), INDENT.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	1.10
A1	0.05	0.10	0.15
A2	0.813	0.863	0.914
b	0.28	---	0.38
c	0.139	---	0.23
D	2.90	3.00	3.10
D2	1.50	1.70	1.80
E	4.775	4.876	4.978
E1	2.90	3.00	3.10
E2	1.14	1.40	1.50
e	0.65 BSC		
L	0.40	---	---
L1	0.94 REF		
L2	0.25 REF		
M	0°	---	8°



DETAIL A



RECOMMENDED MOUNTING FOOTPRINT

GENERIC MARKING DIAGRAM\*



- XXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- W = Work Week
- ZZ = Assembly Lot Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

\* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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